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Assistant Commissioner for Patents
Washington, D.C. 20231

On March 3, 2003

TOWNSEND and TOWNSEND and CREW LLP

By: 

PATENT
Attorney Docket No.: 16869S-028400US
Client Ref. No.: E6033-01 MR

#11144
T. BELL
3.21.03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Tsutomu Kono, et al.

Application No.: 09/884,784

Filed: June 19, 2001

For: HYBRID HOUSING OF METAL
BOARD AND SYNTHETIC RESIN

Examiner: Hung V. Ngo

Art Unit: 2831

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed October 3, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend the claims as indicated below:

1. (Amended) A housing for electronic equipment comprising:
a metal base board including a first main surface and a second main
surface, said second main surface being provided at an opposing side of said first main
surface, said metal base board having at least one through hole extending from said first
main surface to said second main surface, said at least one through hole being configured
to facilitate an outsert-molding process;

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